

# KMPR® 1000

## Negative Epoxy Photoresists

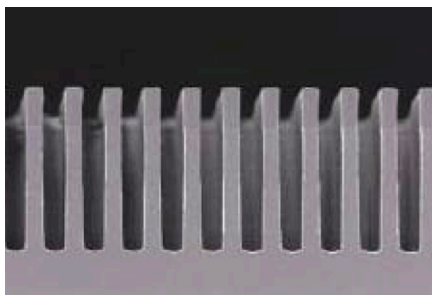
KMPR® 1000 i-Line photoresist is a high contrast, epoxy-based photoresist that can be developed in a conventional aqueous alkaline developer (TMAH) and more easily removed after normal processing. Its excellent adhesion and chemical and plasma resistance make it ideal for various MEMS, electrolytic plating and DRIE applications.

### FEATURES

- High aspect ratio with vertical sidewalls
- > 100 µm film thickness in a single coat
- Good adhesion to most substrates
- Alkaline developer compatible, TMAH and KOH based
- Strippable with wet or dry chemistry
- Excellent dry etch resistance

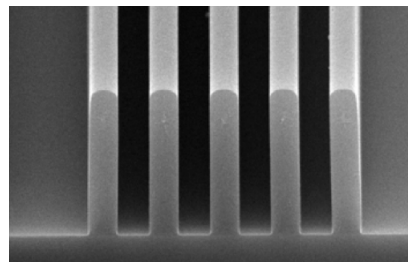
### APPLICATIONS

- Electroplating
- DRIE mask
- MEMS

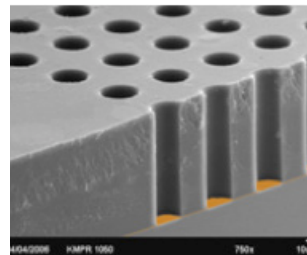


Etch trenches  
10 µm features, 65 µm thick

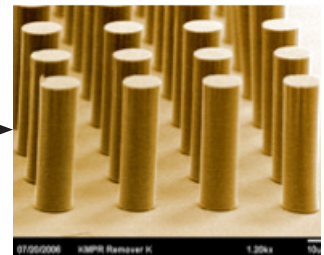
Photo courtesy of ULVAC



10 µm Film Thickness  
2 µm Lines/Spaces



10 µm via structure in 45 µm thick KMPR® on Cu seed layer



Cu plated pillars and KMPR® removed

### PRODUCT LINE

- 5 standard dilutions: 4 – 110 µm in a single step
- KMPR® 1005, 1010, 1015, 1025 and 1035